Advanced PECVD-LS Nitride2(n=1.93,-40MPa, 8.3nm/min)			
SiN depostion~2500A, 300C			
Step1:	**NITRIDE2 coat**		
	Name	**Value**	**Changeable**
	LF on time(ms)	1000ms	Y
	LF setpoint	90W	Y
	Process pressure	800 mtorr	N
	RF on time(ms)	6000ms	N
	RF setpoint	30 W	N
	stabilization time	15 seconds	N
	step time(m)	**10 min**	**Y**
	step time(s)	**0 sec**	**Y**
	2%SiH4 %He	1040sccm	N
	N2	980sccm	N
	NH3	18sccm	N
Step2:	**NITRIDE2 deposition**		
	Name	**Value**	**Changeable**
	LF on time(ms)	1000ms	Y
	LF setpoint	90W	Y
	Process pressure	800 mtorr	N
	RF on time(ms)	6000ms	N
	RF setpoint	30 W	N
	stabilization time	15 seconds	N
	step time(m)	**30 min**	**Y**
	step time(s)	**0 sec**	**Y**
	2%SiH4 %He	1040sccm	N
	N2	980sccm	N
	NH3	18sccm	N
Step3: STANDARD PLASMA CLEAN			
	1. pump down		
	Name	**Value**	**Changeable**
	stabilization time	15 seconds	N
	step time(m)	0	N
	step time(s)	30	N
	2. Pre-purge		
	Name	**Value**	**Changeable**
	purge	**1 (Yes/No)**	N
	stabilization time	15 seconds	N
	step time(m)	**1**	**N**
	step time(sec)	0	N
	3.1 High Pressure		
	Name	**Value**	**Changeable**
	Cload position	**50%**	**N**
	Ctune position	**50%**	**N**
	DriveMatch	**1 (Yes/No)**	**N**
	Process pressure	600 mtorr	N
	RF setpoint=300	300 W	N
	Stabilization time	35 seconds	N
	step time(m)	ENTER TIME	Y
	step time(s)	0	Y
	CF4/O2(5)	500 sccm	N

Advanced PECVD Typical Film Properties

Calibrated every 2-4 weeks

Check for the latest update on UCSB Nanofab WIKI

LS Nitride2~2500A Typical Film Properties

Deposition rate=8.3nm/min

Refractive index@632.8nm=1.932

Stress=-46MPa

HF etch rate=46nm/min

For 7min(coat+deposition) run 1min Standard Plasma Clean